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Inventor: PATENT application of:

Takeshi FUKADA et al.

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Art Unit: 2825

Serial No. 09/904,906

Examiner: Unassigned

Filed: 07/16/2001

For: GLASS SUBSTRATE ASSEMBLY,

SEMICONDUCTOR DEVICE AND METHOD

OF HEAT-TREATING GLASS SUBSTRATE

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class  
mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on 5/3 2002.

**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents and Trademarks

Washington, D.C. 20231

Sir:

In accordance with the duty of disclosure as set forth in 37 C.F.R. § 1.56, Applicants hereby submit the following information in conformance with 37 C.F.R. §§ 1.97 and 1.98. Pursuant to 37 C.F.R. § 1.98, copies of the documents cited are enclosed.

EP 0 225 470 and U.S. Patent Nos. 5,069,531 and 5,109,292 are in the family of JP 62-112128.

These documents are being submitted before the first Office Action on the merits, therefore no fee or certification is required under 37 C.F.R. § 1.97(b).

Respectfully submitted,

  
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